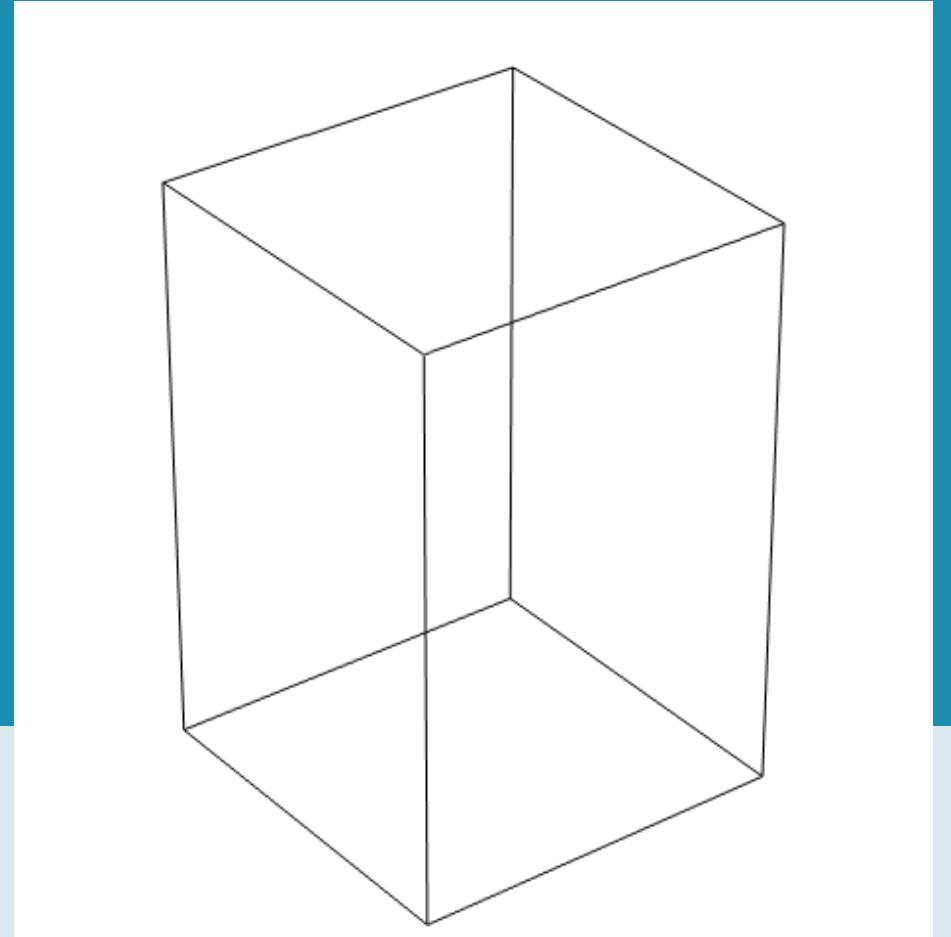




# Investigation for thermal analysis in COMSOL for fused filament fabrication

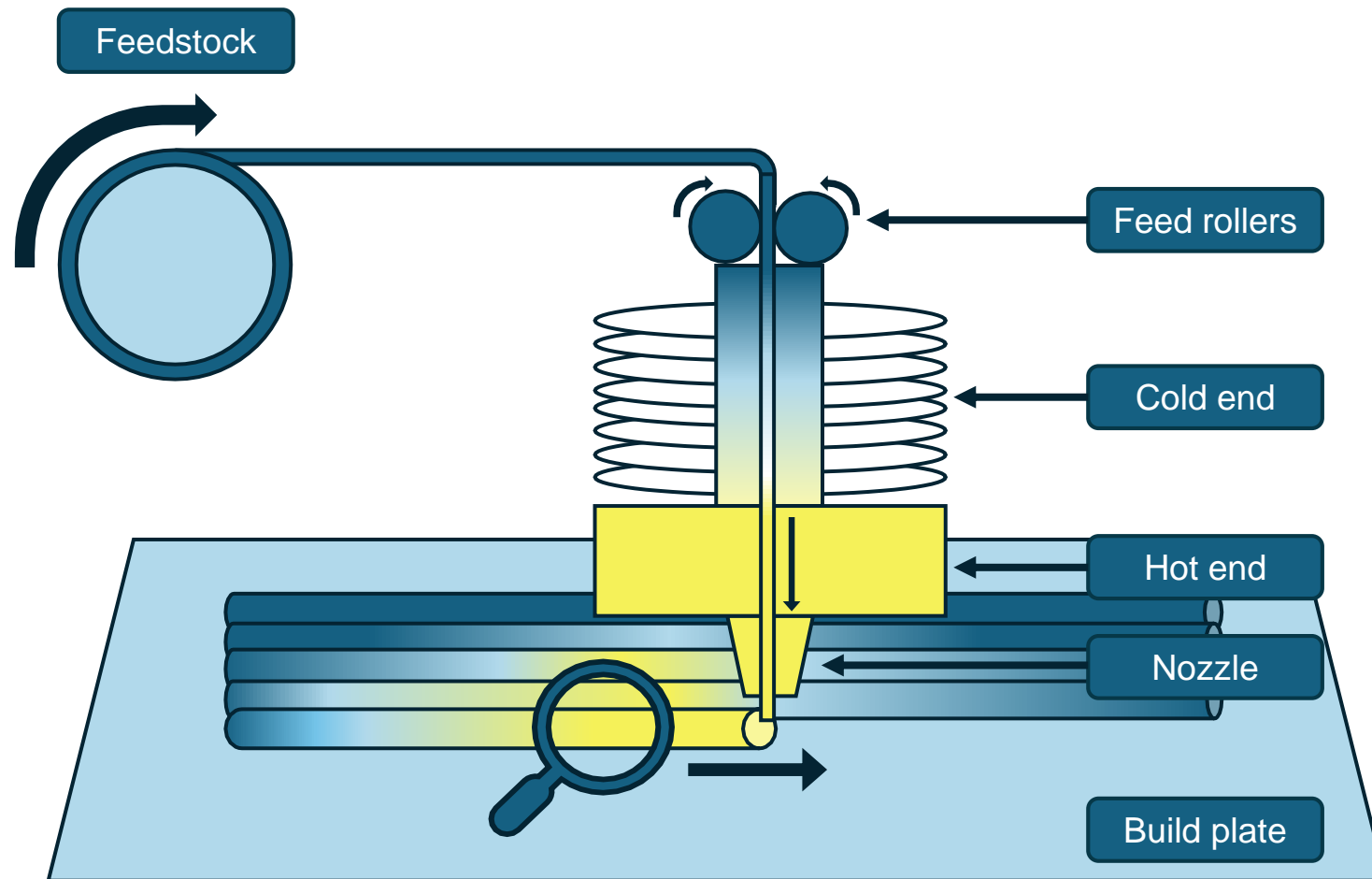


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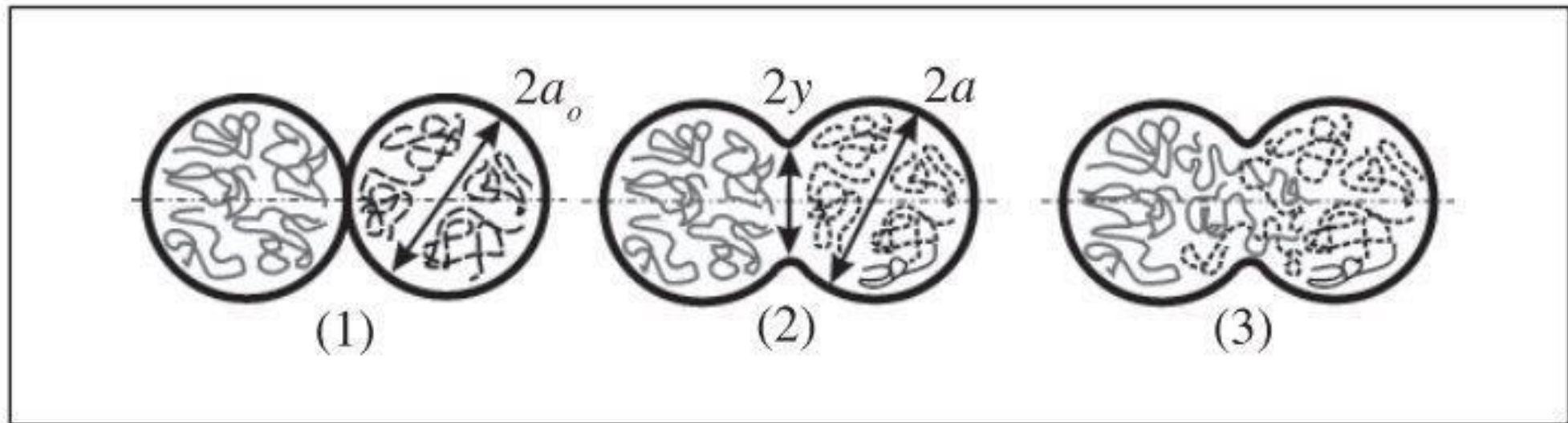
# Fused Filament Fabrication (FFF)



Working principle of the Fused Filament Fabrication technology

# Importance of build temperature in FFF

- Diffusion at the interface
- Temperature criterion for the (glass) phase transition ( $T > T_c$ )
- Cooling pattern during printing is essential

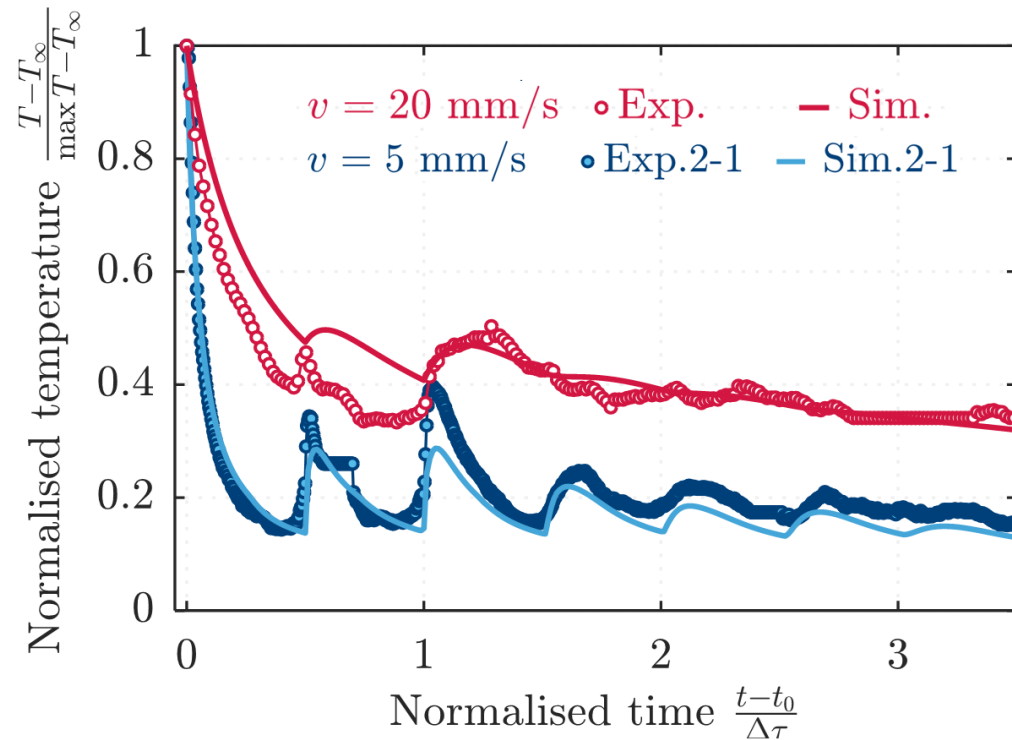


Evolution of bond formation: (1) neck formation (2) neck growth (3) diffusion at interface

# Importance of build temperature in FFF

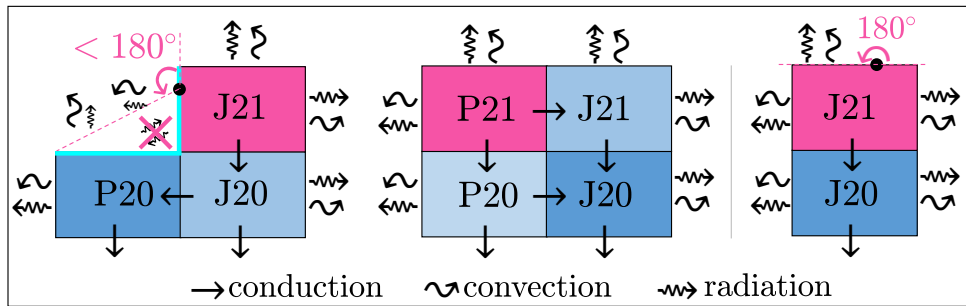
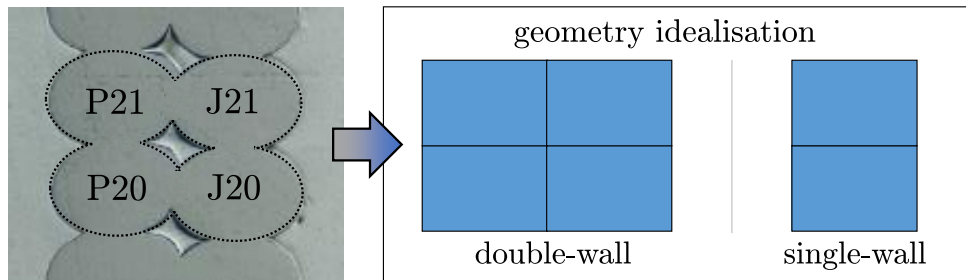
## Coupled-Multiphysics

- polymer melt flow
- heat transfer
- phase change



Comparison of printing speed influence on temperature and print quality

# T4F3 simulation code



Types of energy transportation between elements

**T4F3**

Simulate Help More info Analyse

**Geometry**

length, width, height [mm] 18 0.8 0.6

**Material properties**

density  $\rho$  [g/cm<sup>3</sup>]  Constant  Dynamic  
give me a # 1.24

cp [J/g/K]  Constant  Dynamic  
give me a # 2

Thermal conductivity  $\lambda_x$  [W/m/K] 0.23

Conduction anisotropy?  No  Yes  
 $\lambda_y/\lambda_x$  1  
 $\lambda_z/\lambda_x$  1

Emissivity  $\epsilon_p$  0.78

**Process parameters**

Nozzle Tem.  $T_n$  [°C] 200

Plate Tem.  $T_p$  [°C] 60

Room Tem.  $T_\infty$  [°C] 25

$T_a = T_a(z)$  [°C]  1  9.443  25

Printing speed  $v$  [mm/s] 5

Convection coeff.  $h$  [W/m<sup>2</sup>/K] 8.5

Strand width  $w$  [mm] 0.4

Layer thickness  $h$  [mm] 0.3

Wide flat nozzle tip [mm] 0

Radiation from hot-end?  No  Yes

$L$   $W$   $z_0$   $\epsilon_n$

30 16 2 0.95

**Sim. parameters**

How long to run the sim. 1

Natural conv. after finish? 8.5

Element number in x dir. 41

File name for data test

**T4F<sup>3</sup> : Temperature for Fused Filament Fabrication**

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You can proceed to analyse ...  
(This figure shows the temperature on the middle of the first track on the first layer)

Temperature [°C]

Time [s]

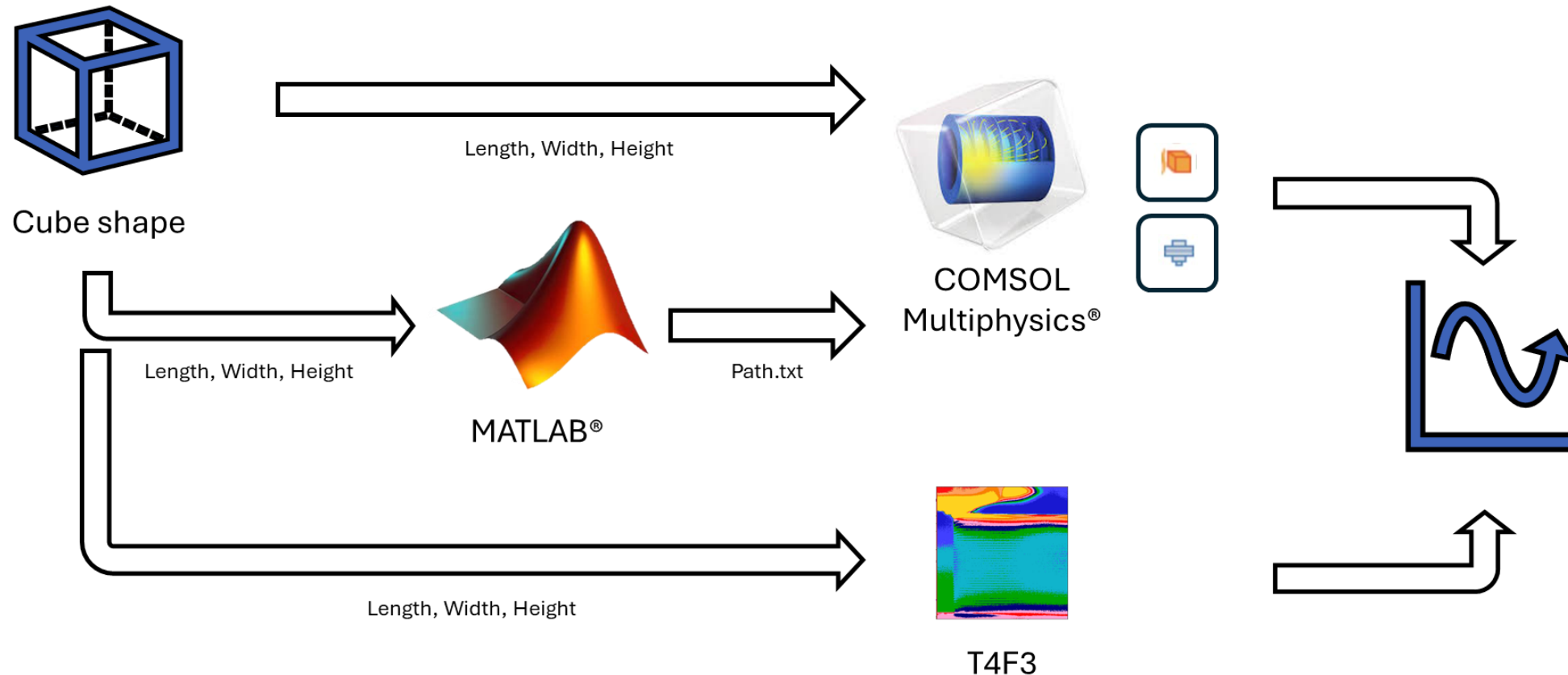
Estimate data size

Check stability

Run the simulation

Interface T4F3-software to calculate temporal temperature

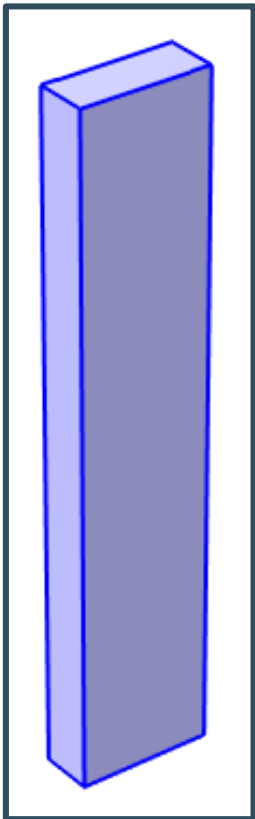
# Validation methodology



Overview of working method used in this study to compare T4F3 with COMSOL

# MATLAB implementation

## Input



## MATLAB-code

```
for z = z_list
    for y_index = 1:length(y_list)
        for x = x_list
            dist = sqrt((data.X(end)-x)^2+((data.Y(end)-y)^2));
            time = time + dist / printingSpeed;
            new_row = {time, x, y, z};
            data(row_counter, :) = new_row;
            row_counter = row_counter + 1;
        end
    end
end
```

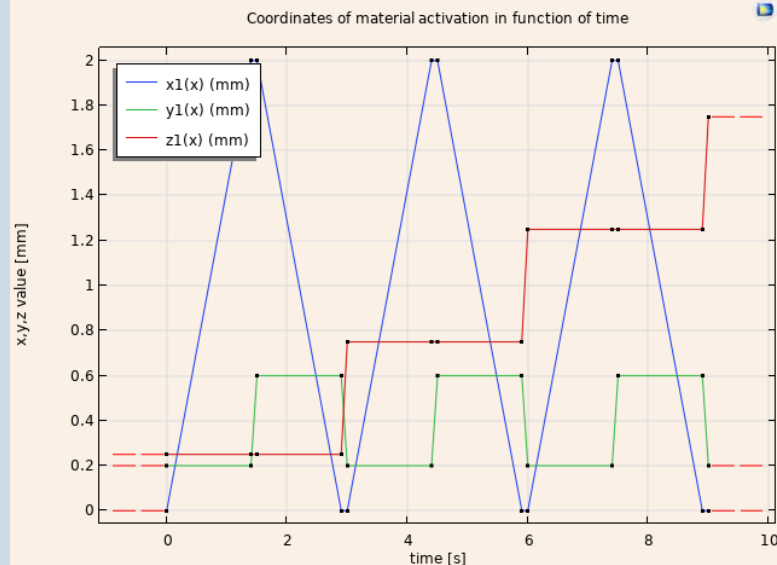


## Output

t(s)	x	y	x
0	0	0.2	0.25
1.4	18	0.2	0.25
1.5	18	0.6	0.25
2.9	0	0.6	0.25
3	0	0.2	0.75
4.4	18	0.2	0.75
4.5	18	0.6	0.75
5.9	0	0.6	0.75
6	0	0.2	1.25
7.4	18	0.2	1.25
7.5	18	0.6	1.25
8.9	0	0.6	1.25
9	0	0.2	1.75

# COMSOL implementation

## Interpolation & Activation



If

$(\text{abs}(x-x_1(t)) \leq x\_length/4$   
&&  $\text{abs}(y-y_1(t)) \leq \text{Strand\_width}/2$   
&&  $\text{abs}(z-z_1(t)) \leq \text{Layer\_height}/2$   
,1,0)

## Heat transfer module



Solid:

- Thermal cond., density, heat capacity → user defined
- If(solid.isactive, PLA, Air)

Temperature:

- Build plate temperature

Heat source:

- Go to  $T_{\text{nozzle}}$  at activation function location

Heat flux:

- Convection at boundary

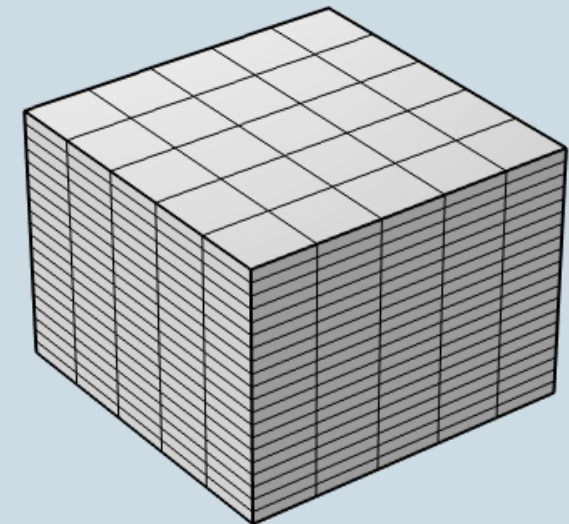
## Mesh



Cubic mesh

Mesh size:

- Y: Size of strand
- Z: Layer height/4

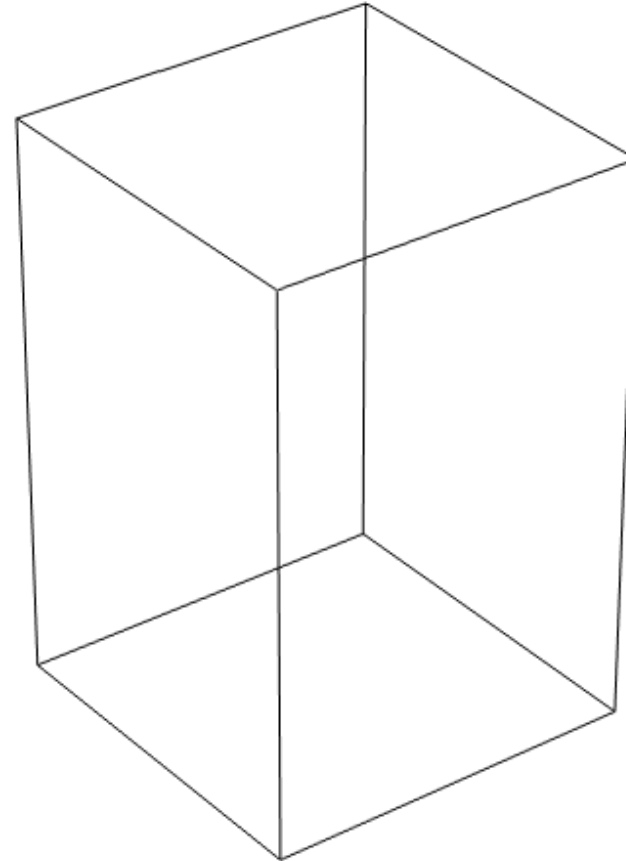




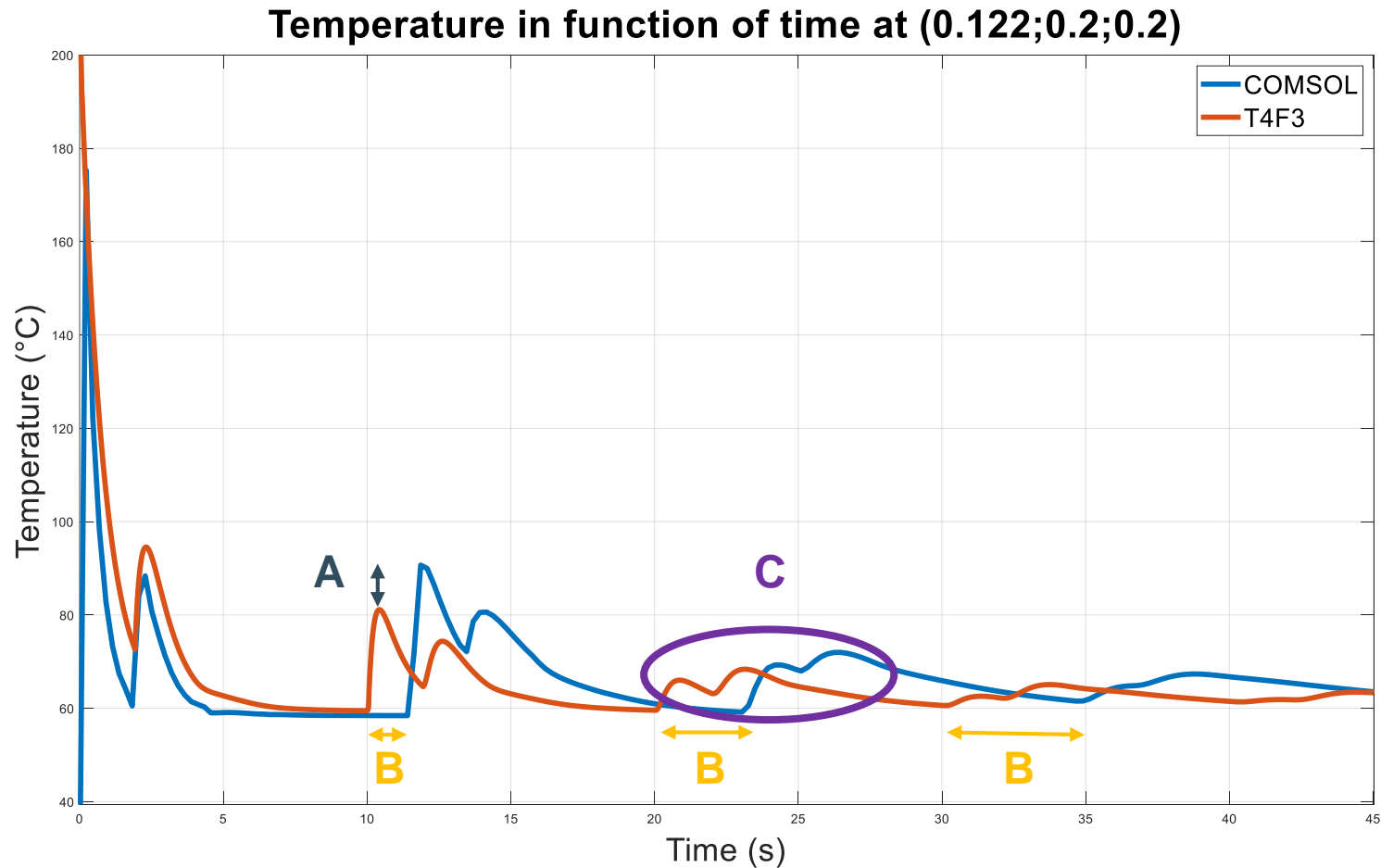
# Preliminary results

## Simulation settings

- 4x4x6 mm cube
- Printing speed 5 mm/s
- PLA print material
- $T_{\text{nozzle}} = 200^{\circ}\text{C}$
- $T_{\text{build plate}} = 60^{\circ}\text{C}$
- $T_{\text{room}} = 20^{\circ}\text{C}$



# Preliminary results: Comparison to T4F3



## A: Different temperature peaks

- Data collection method
- Source temperature difference
- Cooling rate difference

## B: Time shifts

- Different path generation

## C: Similar effect next layers

- More analysis of patterns is needed

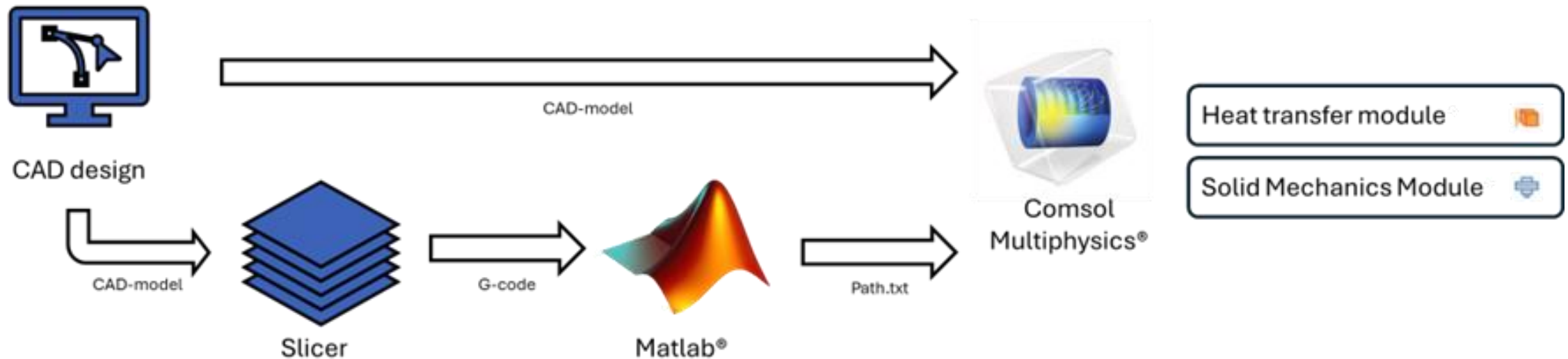
# Conclusion

## New insights

- Workflow for use of COMSOL in FFF thermal simulation
- Conversion from T4F3 results

## Future work

- Improve current model (accuracy and calculating efficiency)
- Make step towards free-form simulations



# Thank you!

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# References

[1] Bellehumeur, C., Li, L., Sun, Q., & Gu, P. (2004). Modeling of Bond Formation Between Polymer Filaments in the Fused Deposition Modeling Process. *Journal of Manufacturing Processes*, 6(2), 170–178.

[https://doi.org/10.1016/S1526-6125\(04\)70071-7](https://doi.org/10.1016/S1526-6125(04)70071-7)

[2] J. Zhang, B. Van Hooreweder, and E. Ferraris, “T4F3: temperature for fused filament fabrication,” *Progress in Additive Manufacturing*, vol. 7, no. 5, pp. 971–991, Oct. 2022, doi: 10.1007/S40964-022-00271-0/FIGURES/15.